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2. Name _____

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	U	Inventor	Document	Issue P	Title	Current	Current X	Retrieval S	C	P	Image Do P
1		Bartley, Ge	US 608477	2000	7	Heatsink and package structures with	361/70	165/80.3			US 608477
2		Lee, Yong-	US 200402	2004	1	Flip chip package having protective ca	257/77				US 200402
3		Arnold, Roc	US 200402	2004	3	Electromagnetic interference shielding	361/80				US 200402
4		Homung, C	US 200402	2004	1	Dual material heat sink core assembly	361/70				US 200402
5		Soule, Chri	US 200302	2003	1	Stacked fin heat sink and method of m	257/70	257/E23.1			US 200302
6		Lin, Yu-Se	US 200301	2003	1	Heat sink for heat-susceptible electron	165/80	257/E23.0			US 200301
7		Patel, Chan	US 200201	2002	1	Cooling plate arrangement for electron	361/70				US 200201
8		Patel, Chan	US 668712	2004	1	Cooling plate arrangement for electron	361/70	361/687			US 668712
9		Innes, Rob	US 644426	2002	1	Apparatus and method for cooling she	427/35	118/123			US 644426
10		Lipinski, Jo	US 583871	1997	1	Method and apparatus for fabricating	72/178	29/890.03			US 583871